

WHAT IS CLAIMED ARE:

1. A heat-dissipating module of an integrated circuit of a portable computer comprising:

a thermal pad positioned on said integrated circuit; and

a heatsink fixed to said thermal pad and having a non-rectangular contact surface contacting with said thermal pad so as to dissipate a heat produced from said integrated circuit.

2. The heat-dissipating module of an integrated circuit of a portable computer according to claim 1, wherein said non-rectangular contact surface has a circular shape.
3. The heat-dissipating module of an integrated circuit of a portable computer according to claim 1, wherein said heatsink has a main portion and an extension portion.
4. The heat-dissipating module of an integrated circuit of a portable computer according to claim 1, wherein a phase-transition material is added to said thermal pad and said heatsink.
5. The heat dissipating module of an integrated circuit of a portable computer according to claim 1, wherein said heat dissipating module further comprises a heatpipe.
6. The heat dissipating module of an integrated circuit of a portable computer according to claim 1, wherein said heat dissipating module further comprises a fan.